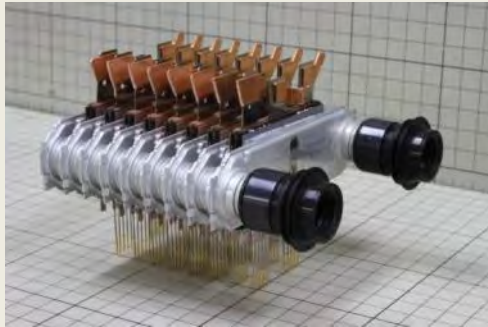


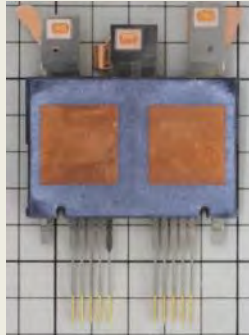
DENSO POWER CARD MODULE STRUCTURE ANALYSIS REPORT

– Product used in the Toyota YARIS

LTEC Corporation released a detailed structure analysis reports of the Denso power card used in the Toyota Yaris PHEV.



Inverter unit



Power card



IGBT die

Product overview

In February 2020 Toyota has renamed their compact car model to 'Yaris' and re-designed the entire system.

There are eight Denso power cards in the power module: three for motor drive, three for charging, and two for voltage boost. There are two RC-IGBT chips mounted on each power card. Relative to the inverter used in the Prius, 30% size reduction was achieved.

Report content

- 1. Power card structure analysis report:** The 62-page report includes structural details, module appearance, X-ray observations, plane view analysis, cross section analyses, material analysis and thermal analysis. **(Sales price: \$3,500)**
- 2. RC-IGBT structure analysis:** The 79 pages report includes structural details, plane view SEM observations and SEM cross sections of the cell area and die edge. **(Sales price: \$4,000)**
- 3. Option report 1:** Teardown of each modules (motor drive, charging and voltage boost) including each IGBT die image **(Sales price: \$2,500)**
- 4. Option report 2:** Carrier concentration profile analysis by Spreading Resistance Profiler analysis of RC-IGBT back side **(Sales price: \$2,500)**

Note: The report price may change over time. For current price contact info@ltecusa.com.

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Table of Contents

Power card structure analysis report

	Page
<u>Device summary</u>	
Table 1, Executive Summary	3
Analysis results summary	5
<u>Module analysis</u>	
Module overview	9
Power card overview	11
<u>Power card analysis</u>	
Plane view analysis	16
<u>Cooling method analysis</u>	
Cooling method overview	21
Cooling method details	26
<u>Power card cross section</u>	
SEM cross section	29
SEM-EDX	53
<u>Thermal analysis</u>	
Thermal analysis modeling	57
Thermal resistance calculation of double side power card	59
Thermal resistance calculation of water cooling heat sink	60
Thermal resistance calculation of entire module	61



Table of Contents

IGBT structure analysis report

	Page
<u>Device summary</u>	
Table 1, Executive Summary	3
Analysis results summary	4
<u>Package overview</u>	
Package overview	11
X-ray	11
<u>IGBT structure analysis</u>	
Layout	18
Plane view observation (OM)	19
Plane view observation (SEM)	46
Cross section (Cell area top side)	61
Cross section (Cell area back side)	70
Cross section (Die edge)	73



